

# **INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20487**

Generic Copy

#### Issue Date: 11-Jun-2014

TITLE: Initial Notification of SOT-553 and SOT- 563 package/devices qualification for assembly & test in Leshan, China

#### PROPOSED FIRST SHIP DATE: 17-Nov-2014

AFFECTED CHANGE CATEGORY(S): Assembly and test site

#### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <<u>York.Yu@onsemi.com</u>>

#### **NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

#### **DESCRIPTION AND PURPOSE:**

ON Semiconductor is notifying customers of its plan to qualify and transfer the assembly and test of SOT553 and SOT563 packages from ON Semiconductor Seremban facility to ON Semiconductor Leshan facility.

The ON Semiconductor Leshan facility is certified with ISO/TS 16949:2009.

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#### **QUALIFICATION PLAN:**

Estimated Date for Qualification Completion: 08/28/2014 Samples should be available after completion of Qualification.

# Reliability testing will be performed on qualification vehicles chosen based on die size, voltage rating and run rates.

#	Test	Name	Test Conditions	End Point Req's	Test Results Read Point
1	HTSL	High Temp Storage Life	Ta=150°C	c = 0, Room	1008 Hrs
2	AC+PC	Autoclave+PC	Ta=121°C, RH=100%, Pressure=15psig	c = 0, Room	96 Hrs
3	TC+PC	Temperature Cycle+PC	Ta=-65°C, Tj=150°C, Air-to-air, Dwell = 10 min	c = 0, Room	1000 Сус
4	H3TRB+PC	High Humidity High Temp Rev Bias+PC	Ta=85°C, RH=85%	c = 0, Room	1008 Hrs
5	IOL+PC	IOL+PC	Δ Tj=+25°C, Tj=100°C, On/Off = 2 min	c = 0, Room	15000 Cyc
6	RSH	Resistance to Solder Heat	Ta: 260°C	c = 0, Room	n/a
7	HTRB+PC	High Temp Reverse Bias + PC	Ta=150°C	c = 0, Room	1008 Hrs





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For automotive customers currently purchasing the standard/commercial parts as stated in table below, the backlogs can be transferred to the respective automotive parts or special parts. The automotive parts are targeted to be transferred to Leshan facility by 25- Sep- 2015.

Std Part	Auto Part
NSS12100XV6T1G	NSV12100XV6T1G
NST30010MXV6T1G	NSVT30010MXV6T1G
NST3904DXV6T5G	SNST3904DXV6T5G
BC847CDXV6T1G	SBC847CDXV6T1G
BAS16DXV6T1G	SBAS16DXV6T1G
NST3904DXV6T1G	NSVT3904DXV6T1G
NSBC123JPDXV6T5G	NSVB123JPDXV6T1G
NSBC114YDXV6T1G	NSVBC114YDXV6T1G
NSBC143TPDXV6T1G	NSVB143TPDXV6T1G
NL17SZ04XV5T2G	SL17SZ04XV5T2G
EMX1DXV6T1G	NSVEMX1DXV6T1G
NSBC144EPDXV6T1G	NSVB144EPDXV6T1G
NSBC143ZPDXV6T1G	NSVB143ZPDXV6T1G

Std Part	Auto Part
BC847BPDXV6T1G	SBC847BPDXV6T1G
NSBC124XPDXV6T1G	NSVB124XPDXV6T1G
NSBC124EDXV6T1G	NSVBC124EDXV6T1G
NSBA114YDXV6T1G	NSVBA114YDXV6T1G
EMC2DXV5T1G	NSVEMC2DXV5T1G
NSBC114EDXV6T1G	NSVBC114EDXV6T1G
NSBC114EPDXV6T1G	NSVBC114EPDXV6T1G
NSR0320XV6T1G	NSVR0320XV6T1G
NST30010MXV6T1G	NSVT30010MXV6T1G
NST3904DXV6T1G	SNST3904DXV6T1G
NST3906DXV6T1G	NSVT3906DXV6T1G
NST3946DXV6T1G	NSVT3946DXV6T1G
NZQA6V8XV5T1G	SZQA6V8XV5T1G

Std Part	Special part
NUF2042XV6T1G	SNUF2042XV6T1G
NTZD3152PT1G	STZD3152PT1G
NTZD3154NT1G	STZD3154NT1G
NTZD3155CT1G	STZD3155CT1G
NTZD3155CT2G	STZD3155CT2G

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#### List of affected General Parts:

#### List of affected Customer Specific Parts:

STZD3155CT1G